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LETTERS

Small-Signal Substrate Resistance Effect in RF CMOS Cascode Amplifier	C.-Y. Cha, J.-P. Kim, and S.-G. Lee	253
Controllability of Novel $\text{Sn}_{0.95}\text{Au}_{0.05}$ Microbumps Using Interlaminated Tin and Gold Layers for Flip-Chip Interconnection	K. Onodera, T. Ishii, S. Aoyama, and M. Tokumitsu	256
Low Noise 5 GHz Differential VCO Using InGaP/GaAs HBT Technology	Y. Eo, K. Kim, and B. Oh	259
Waveguide-to-Microstrip Transition With Integrated Bias-T	C. Risacher, V. Vassilev, A. Pavolotsky, and V. Belitsky	262
Effective Permittivity at the Interface of Dispersive Dielectrics in FDTD	D. Popovic and M. Okoniewski	265
Efficient Implementation of the Cauchy Method for Automated CAD-Model Construction	A. Lamecki, P. Kozakowski, and M. Mrozowski	268
Simplified RF Receive Frontend Architecture for Active Array Applications	K. Solbach	271
An Improved Leaded Small Outline Package and Equivalent Circuit	D. Jessie and L. Larson	273
Fully Integrated Unequal Wilkinson Power Divider With EBG CPW	Y.-J. Ko, J.-Y. Park, and J.-U. Bu	276
Wideband and Compact Bandstop Filter Structure Using Double-Plane Superposition	J.-Y. Kim and H.-Y. Lee	279
On Miniaturization Isolation Network of an All-Ports Matched Impedance-Transforming Marchand Balun	M. Chongcheawchamnan, C. Y. Ng, K. Bandudej, A. Worapishet, and I. D. Robertson	281
High-Linearity Class B Power Amplifiers in GaN HEMT Technology	S. Xie, V. Paidi, R. Coffie, S. Keller, S. Heikman, B. Moran, A. Chini, S. P. DenBaars, U. Mishra, S. Long, and M. J. W. Rodwell	284
A Fully Integrated 5.8 GHz U-NII Band $0.18\text{-}\mu\text{m}$ CMOS VCO	Y.-K. Chu and H.-R. Chuang	287

ANNOUNCEMENTS

Call for Papers—IEEE Conference on Ultra Wideband Systems and Technologies	290
IEEE Copyright Form	291
